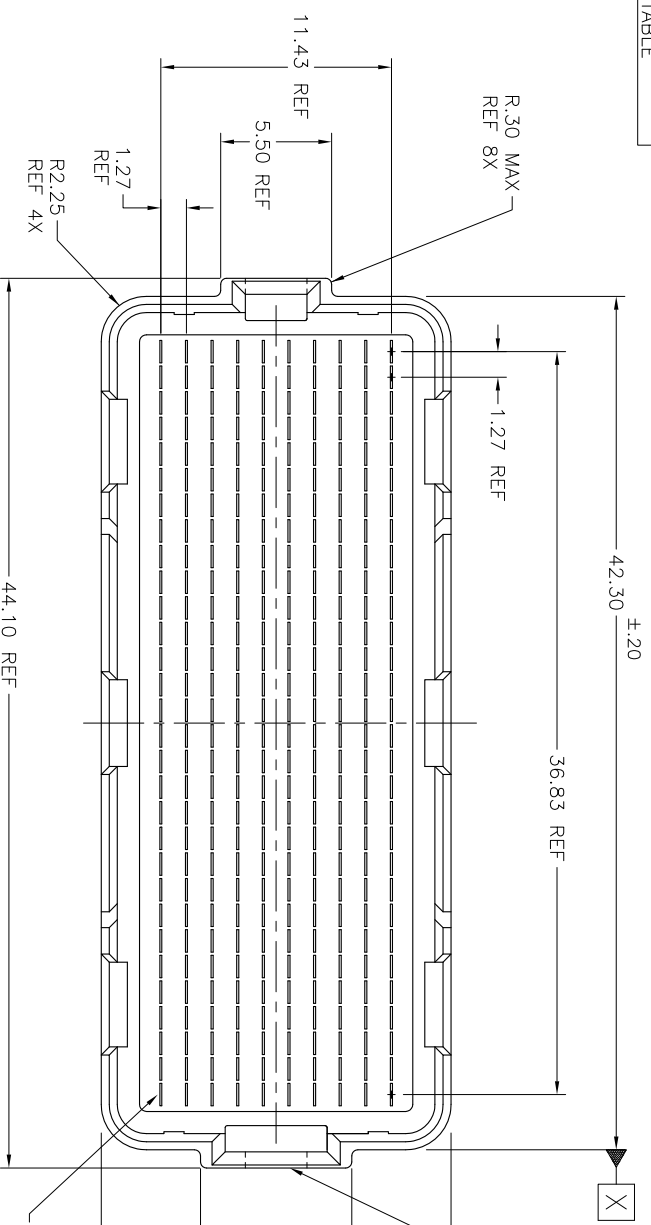


PRODUCT NUMBER
SEE TABLE

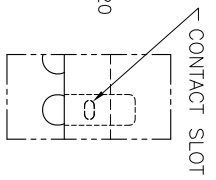
1 2

3

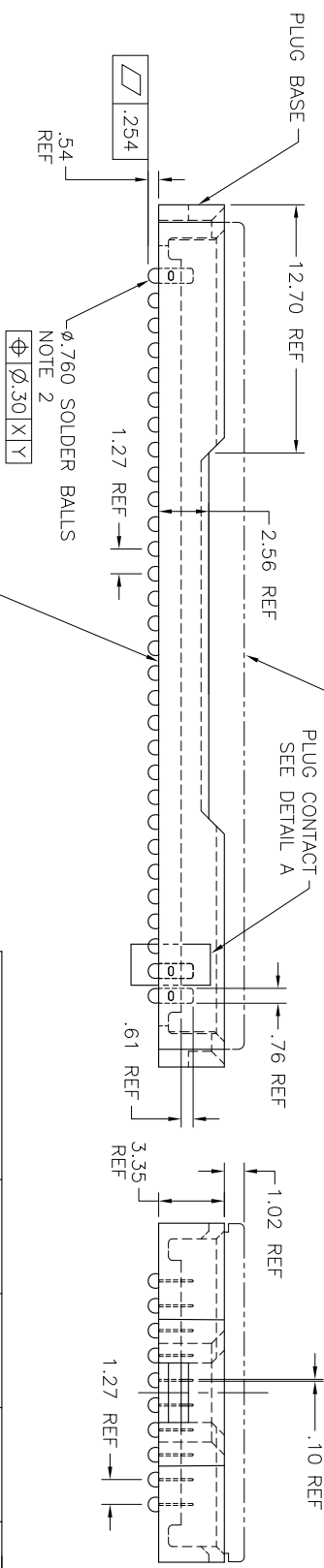
4



OPEN KNT LINES PERMISSIBLE IN PLASTIC BASE COMPONENT KEY SLOT AREAS (BOTH ENDS). SEE NOTE 8.



DETAIL A
SCALE 6:1



CONTINUOUS OPEN KNT LINE CRACKS (TRAVERSING THE ENTIRE BODY LENGTH OF THE CONNECTOR) WHICH CAUSE CRITICAL-TO-FUNCTION DIMENSIONAL CHANGES THAT AFFECT THE CONNECTORS MECHANICAL ALIGNMENT FEATURES ARE NOT PERMISSIBLE. SEE NOTE 6.

mat'l code	surface	tolerance	projection	product family
SEE NOTE 1.	ASME Y14.5	ASME Y14.5	MM	MEG-ARRAY
lfr	ecn no.	dr	date	title
A	V05-0324	DAI	2006/04/19	0mm PLUG ASSY
B	V06-0560	LP	2006/07/18	10 X 30 = 300 POS.
C	V08-0084	LP	2008/05/07	
D	V-13789	DCH	2012/1/21	
		engr	DINGRAM	7/21/04
		chr	D.HARPER	7/21/04
		appd	D.HARPER	7/21/04
sheet index	revision	1	2	3
Sheet	Sheet	1	2	3



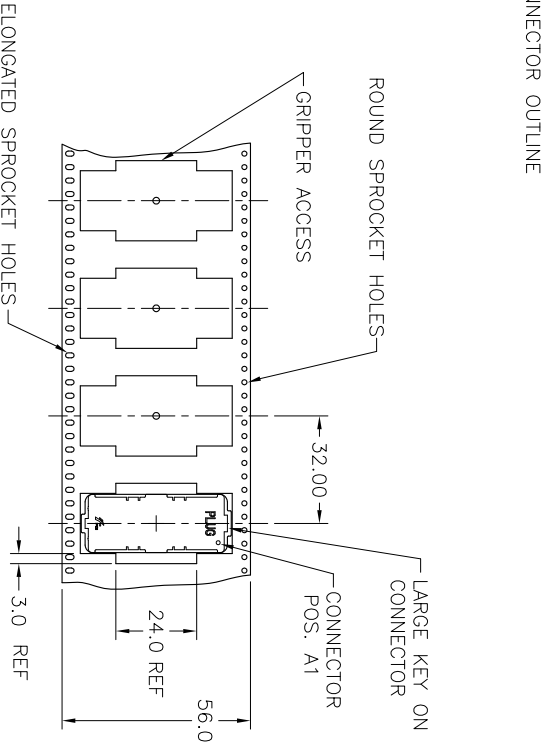
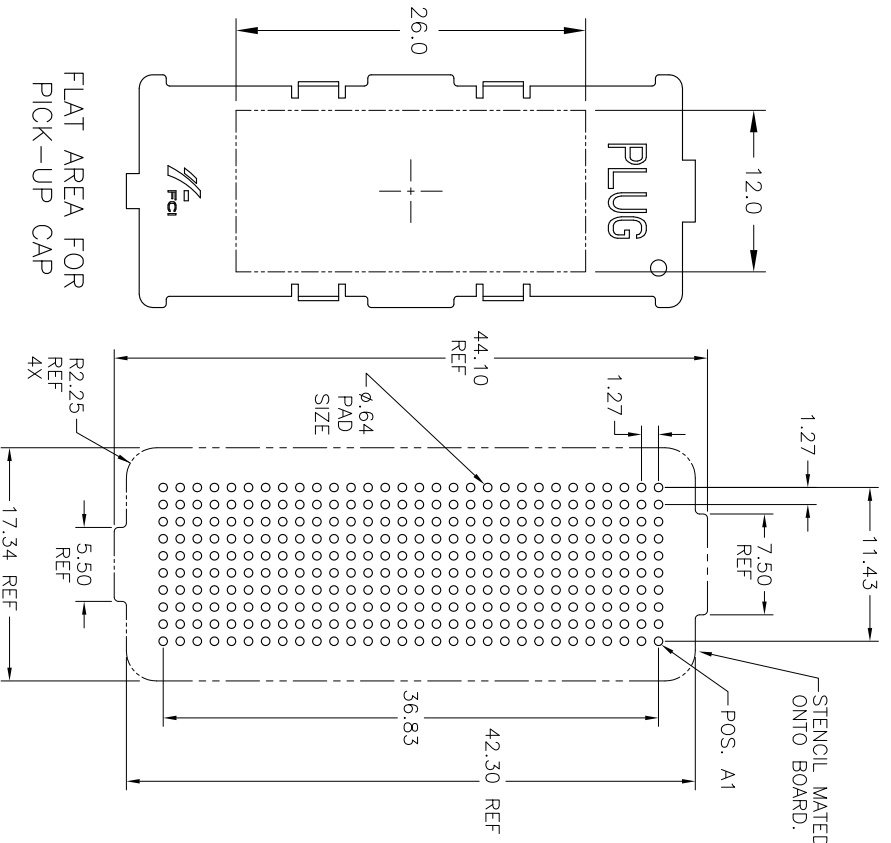
dwg no 10043343
sheet 1 of 3
size A4
CUSTOMER Drawing

PRODUCT NUMBER
SEE TABLE

1 2

3

4



TAPE & REEL PACKAGING SCALE: NONE
PER EIA 481-3

CONFIDENTIAL

mat'l code	surface	tolerance	projection	product family
SEE NOTE 1.	ASME Y14.5	ASME Y14.5	MM	MEG-ARRAY
lit	ecn no	dr	date	title
				0mm PLUG ASSY
D	angles	XX+3	Scale: 2:1	10 X 30 = 300 POS.
	0° ±2'	XX+13		sheet 2 of
		XXX+051		10043343
	dr	D.INGRAM	7/21/04	CUSTOMER Drawing
	engr	D.HARPER	7/21/04	
	chr	D.HARPER	7/21/04	
	appd	D.HARPER	7/21/04	
sheet index	revision			



PRODUCT NUMBER	PICK-UP CAP	CONTACT PLATING	SOLDER BALL
10043343-102			SnPb
10043343-102LF	YES	30u" (0.76um) Au OVER Ni	SnAgCu LEAD FREE (6)(7)
10043343-192			SnPb
10043343-192LF	YES	30u" (0.76um) GXT OVER Ni	SnAgCu LEAD FREE (6)(7)
10043343-202			SnPb
10043343-202LF	YES	50u" (1.27um) Au SPECIAL	SnAgCu LEAD FREE (6)(7)
10043343-292			SnPb
10043343-292LF	YES	50u" (1.27um) GXT SPECIAL	SnAgCu LEAD FREE (6)(7)

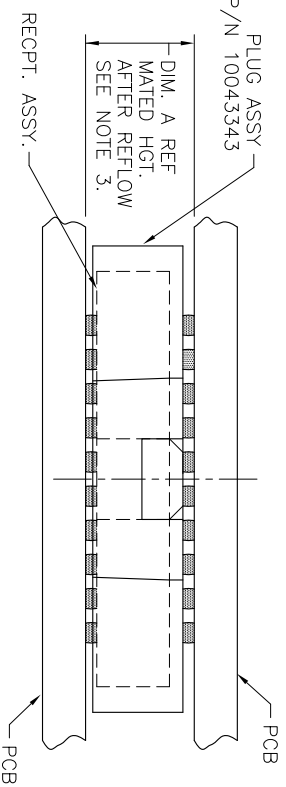
NOTES:

- ① MAT'L:
HOUSING: LCP
CONTACT: COPPER ALLOY

PLATING:

CONTACT: (SEE TABLE ON SHEET 3)
SOLDER BALL: (SEE TABLE ON SHEET 3)
EUTECTIC SnPb OR LEAD FREE
95.5Sn/4Ag/0.5Cu

- ② SOLDER BALLS WILL NOT BE PERFECT SPHERICAL SHAPE DUE TO REFLOW ATTACHMENT.
- ③ MATED HEIGHT EFFECTED BY CUSTOMER'S PCB PAD SIZE, PLATING, SOLDER REFLOW PROFILE, & SOLDER PASTE.
- ④ PLATING FOR INDICATED -2XX SERIES PART NOS. MEETS THE REQUIREMENTS OF CENTRAL OFFICE ENVIRONMENT (25 YEAR LIFE EXPECTANCY).
- ⑤ PLATING FOR INDICATED -2XX SERIES PART NOS. IS Au OR GXT OVER Ni WITH SPECIAL CONTACT GEOMETRY TO MEET REQUIREMENTS OF TELCORDIA GR-1217-CORE: CENTRAL OFFICE ENVIRONMENT.
- ⑥ FOR PROPER APPLICATION FOLLOW FCI APPLICATION SPECIFICATION GS-20-033 LEAD FREE SOLDER BALLS WILL NOT SOLDER PROPERLY IN A LEADED SOLDER PROCESS DUE TO A HIGHER REFLOW TEMPERATURE. LEAD FREE PRODUCT IS THEREFORE NOT BACKWARDS COMPATIBLE WITH LEADED OR SOME SOLDERING APPLICATIONS. REFERENCE FCI APPLICATION SPECIFICATION
- ⑦ THIS PRODUCT MEETS EUROPEAN UNION DIRECTIVES AND OTHER COUNTRY REGULATIONS AS DESCRIBED IN GS-22-008 PRODUCT MEETING THIS DIRECTIVE IS IDENTIFIED IN THE LOT CODE NUMBER MARKED ON EACH PART BY HAVING AN "X" IN THE SEVENTH CHARACTER POSITION
- ⑧ KNOT LINE: SLIGHT VISIBLE MARKS (USUALLY A LINE) THE DIRECTION AND MEETING POINT OF THE PLASTIC RESIN FLOW FRONTS TRAVELING AROUND ANY OBSTRUCTIONS TO THE RESIN FLOW VIA THE REQUIRED MOLD TOOLING.



* 84502 NOT AVAILABLE IN TELCORDIA/NORTEL VERSION.

MATED HEIGHT AFTER REFLOW IS BASED ON Ø .64mm PAD (METAL-DEFINED) AND .13mm SOLDER PASTE STENCIL THICKNESS. SEE NOTE 3.

END VIEW - MATED CONNECTORS SCALE: NONE

mat'l code	surface	tolerance	projection	product family
SEE NOTE 1.	ASME Y14.5	ASME Y14.5	MM	MEG-ARRAY
lit	ecn no	dr	date	tolerances unless otherwise specified
D				X-3
				XX-13
				XXX-051
				Scale 2:1
dr	D:INGRAM	7/21/04		dwg no
engr	D:HARPER	7/21/04		10043343
chr	D:HARPER	7/21/04		sheet 3 of
appd	D:HARPER	7/21/04		10043343
sheet	revision			CUSTOMER Drawing
index	sheet			